

## 80-105GHz Balanced Low Noise Amplifier

### GaAs Monolithic Microwave IC

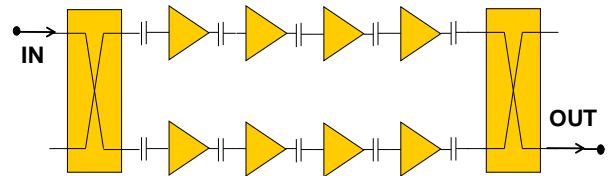
#### Description

The CHA1008-99F is a broadband, balanced, four-stage monolithic low noise amplifier.

It is designed for Millimeter-Wave Imaging applications and can be used in commercial digital radios and wireless LANs.

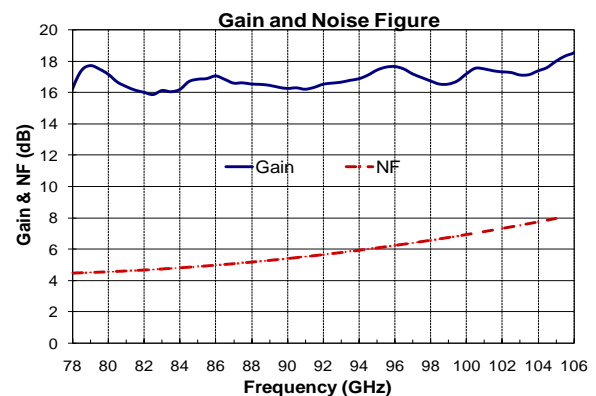
The circuit is manufactured on a pHEMT process, 0.10µm gate length, via holes through the substrate, air bridges and electron beam gate lithography.

It is available in chip form.



#### Main Features

- Broadband performances: 80-105GHz
- Balanced configuration
- 16dB linear gain from 80 to 90GHz
- 5dB noise figure from 80 to 90GHz
- DC bias: VD=2.5V @ ID=115mA
- Chip size 3.40x1.60x0.07mm



#### Main Electrical Characteristics

Tamb.= +25°C

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	80		105	GHz
Gain	Linear Gain (from 80 to 90GHz)		16		dB
NF	Noise Figure (from 80 to 90GHz)		5		dB
Pout	Output Power @1dB comp.		5		dBm

# CHA1008-99F 80-105GHz Balanced Low Noise Amplifier

## Electrical Characteristics

Tamb.= +25°C, VD = 2.5V

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	80		105	GHz
Gain	Linear Gain		17		dB
NF	Noise Figure		[80-90]GHz [90-100]GHz [100-105]GHz	5.0 6.5 7.5	dB
RLin	Input Return Loss		-14		dB
RLout	Output Return Loss		-12		dB
IN/OUT impedance	Input & Output impedance in the chip plan		50		Ohms
OP1dB	Output Power @1dB compression		5		dBm
VG1, VG2	Gate voltages (either on VG1 or VG2 or both on VG1 & VG2)		+0.15		V
VD	Drain voltage		2.5		V
ID	Drain current		115		mA

These values are representative of on-wafer measurements that are made without bonding wires at the RF ports.

## Absolute Maximum Ratings <sup>(1)</sup>

Tamb.= +25°C

Symbol	Parameter	Values	Unit
VD	Drain bias voltage	3	V
ID	Drain bias current	150	mA
VG1, VG2	Gate bias voltage	-2 to +0.8	V
Pin	Maximum peak input power overdrive <sup>(2)</sup>	0	dBm
Tj	Junction temperature	175	°C
Ta	Operating temperature range	-40 to +85	°C
Tstg	Storage temperature range	-55 to +150	°C

<sup>(1)</sup> Operation of this device above any one of these parameters may cause permanent damage.

<sup>(2)</sup> Duration < 1s.

## Typical Bias Conditions

Tamb.= +25°C

Symbol	Parameter	Values	Unit
VD	DC drain voltage	2.5	V
ID	Drain current controlled with VG1 or VG2	115	mA
VG1, VG2	DC gate voltages linked together into the circuit (only one can be used)	+0.15	V

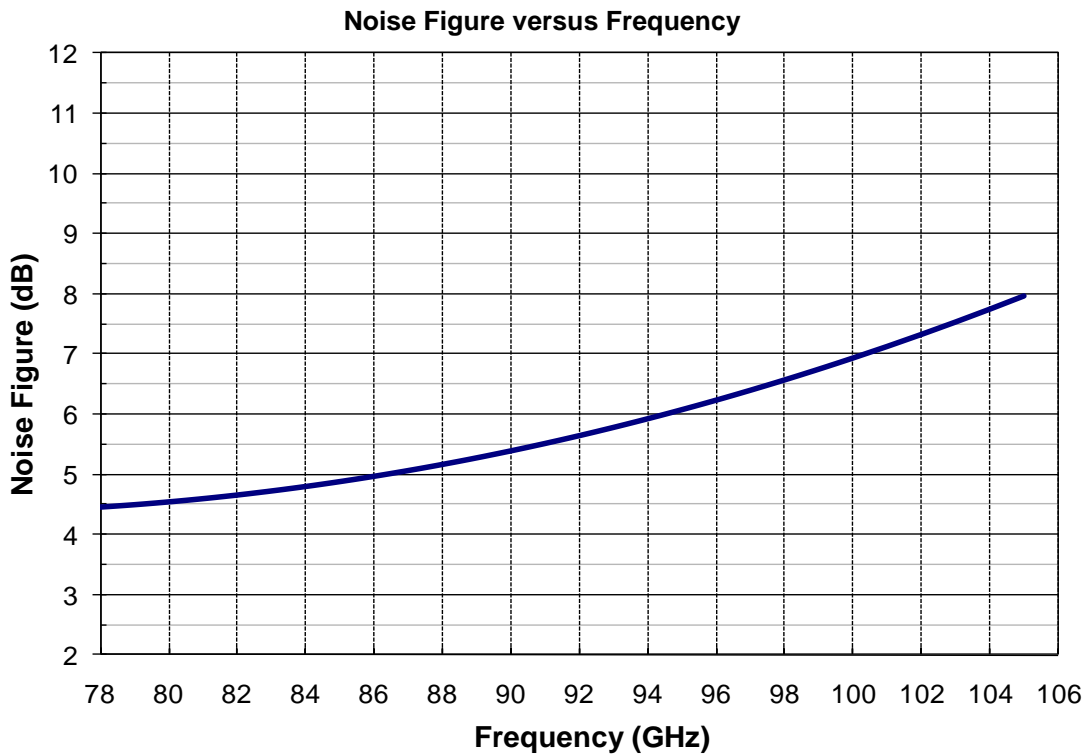
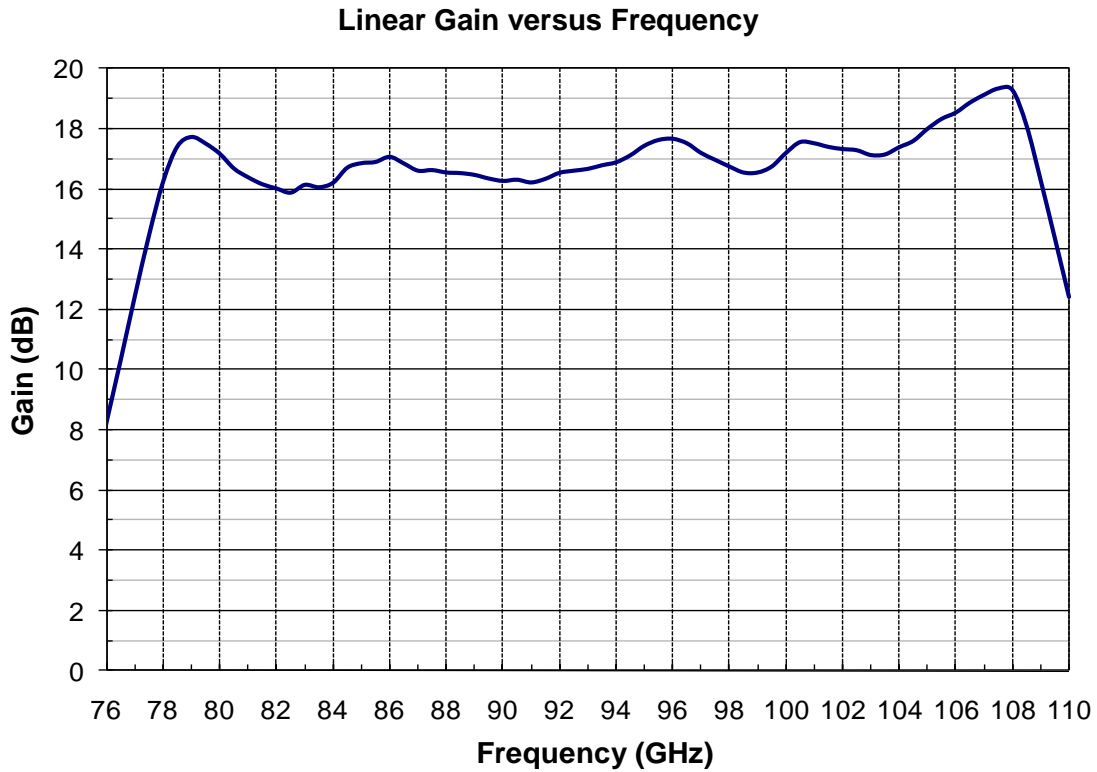
**Typical on-wafer Sij parameters**

Tamb.= +25°C, VD = 2.5V, ID = 115mA

Freq (GHz)	S11 (dB)	PhS11 (°)	S12 (dB)	PhS12 (°)	S21 (dB)	PhS21 (°)	S22 (dB)	PhS22 (°)
70	-9.62	-27.4	-46.61	-1.7	-14.84	-77.4	-19.06	-147.5
71	-7.90	-59.9	-45.20	-29.0	-12.29	-97.7	-23.78	-147.3
72	-6.07	-92.8	-40.60	-79.9	-9.91	-112.3	-15.39	-132.2
73	-4.55	-129.0	-39.39	-141.1	-6.20	-126.5	-15.31	-151.5
74	-2.99	-177.8	-38.67	-178.6	-1.39	-145.8	-16.08	174.2
75	-3.70	112.1	-37.80	122.6	3.76	-175.9	-21.34	156.5
76	-7.04	27.1	-39.02	57.8	8.27	147.2	-32.33	-88.8
77	-9.89	-54.8	-49.41	11.4	12.45	106.5	-25.50	-87.4
78	-11.11	-119.6	-50.15	8.0	16.25	55.7	-15.98	-91.1
79	-15.87	-165.0	-47.11	-33.3	17.72	-1.7	-14.77	-113.8
80	-24.20	173.2	-60.94	-113.5	17.16	-50.1	-12.28	-136.7
81	-28.72	-99.1	-51.00	-67.4	16.38	-88.2	-12.32	-152.4
82	-21.77	-98.6	-48.05	-109.3	16.01	-121.7	-13.09	-159.2
83	-18.19	-113.9	-53.75	-119.6	16.13	-154.9	-11.89	-171.9
84	-16.98	-118.1	-52.54	-161.8	16.20	174.3	-12.21	171.4
85	-15.21	-135.4	-51.74	146.8	16.85	141.8	-13.98	156.7
86	-15.61	-154.4	-52.07	103.4	17.06	107.0	-15.12	152.8
87	-16.28	-162.2	-55.59	-10.9	16.60	73.6	-15.11	154.1
88	-16.82	-172.6	-63.41	-173.6	16.54	44.6	-15.99	144.6
89	-17.77	174.3	-59.12	100.7	16.46	14.0	-16.01	138.5
90	-20.16	162.6	-56.99	37.3	16.26	-16.5	-15.98	127.1
91	-23.37	160.8	-58.98	-48.2	16.21	-45.1	-17.49	117.1
92	-25.07	174.8	-63.88	42.0	16.53	-73.5	-18.31	108.2
93	-27.83	-176.8	-49.55	15.8	16.66	-103.9	-18.51	99.7
94	-24.20	-142.3	-45.20	-14.8	16.88	-132.6	-23.35	82.7
95	-19.58	-159.9	-44.79	-51.8	17.43	-163.4	-27.83	119.0
96	-19.07	169.2	-47.08	-78.6	17.66	160.9	-20.18	121.6
97	-20.34	148.5	-47.05	-86.8	17.19	127.5	-20.52	105.7
98	-21.08	132.2	-46.64	-96.8	16.74	97.5	-20.30	83.3
99	-20.56	115.6	-46.80	-89.2	16.54	69.0	-21.28	67.8
100	-19.37	85.3	-43.63	-90.3	17.19	41.0	-28.63	-10.1
101	-18.31	52.3	-41.25	-106.8	17.51	4.7	-28.04	164.1
102	-16.68	28.0	-40.83	-125.1	17.32	-29.6	-21.86	121.9
103	-14.47	1.7	-43.05	-142.1	17.12	-62.6	-22.99	113.3
104	-13.45	-28.5	-41.39	-138.6	17.38	-94.2	-22.85	74.3
105	-13.48	-46.5	-40.08	-150.1	17.99	-129.8	-30.09	105.1
106	-12.52	-54.9	-40.47	-165.1	18.53	-169.5	-28.68	173.0
107	-11.21	-72.6	-41.80	-163.4	19.12	146.3	-20.32	169.1
108	-11.12	-84.1	-39.92	175.3	19.28	91.4	-12.90	138.1
109	-9.82	-90.7	-36.78	173.2	16.28	29.9	-10.74	106.6
110	-8.67	-109.5	-36.82	159.6	12.41	-8.0	-10.66	76.0

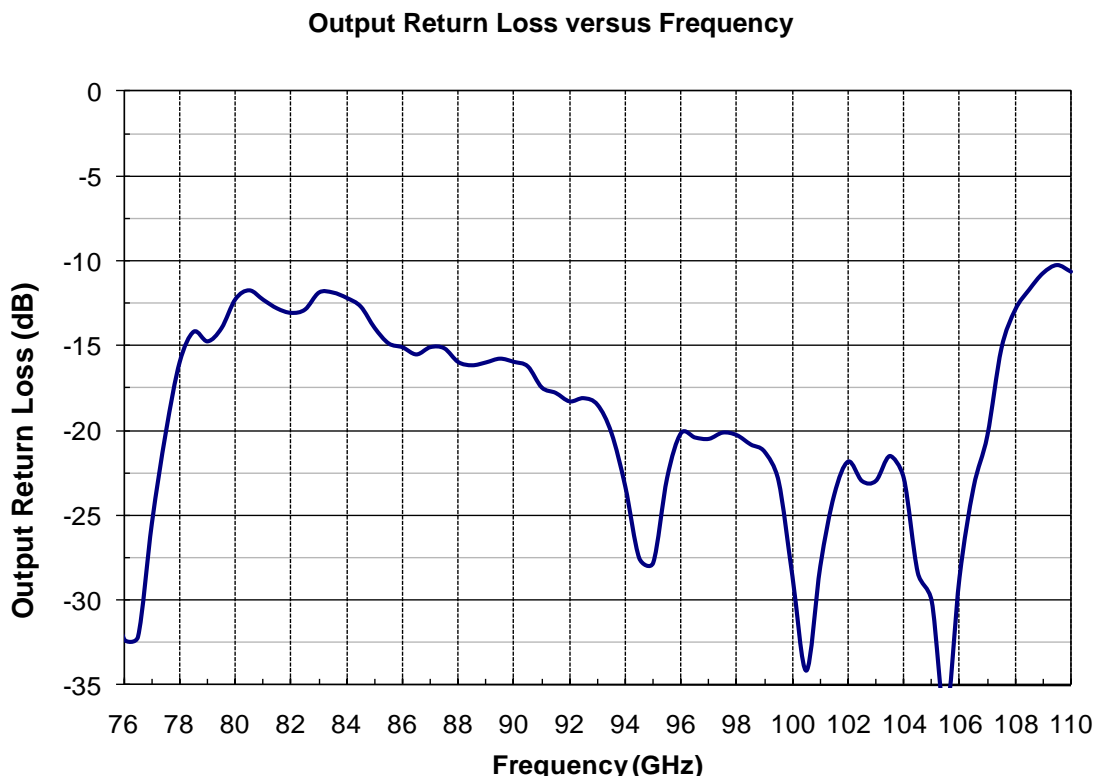
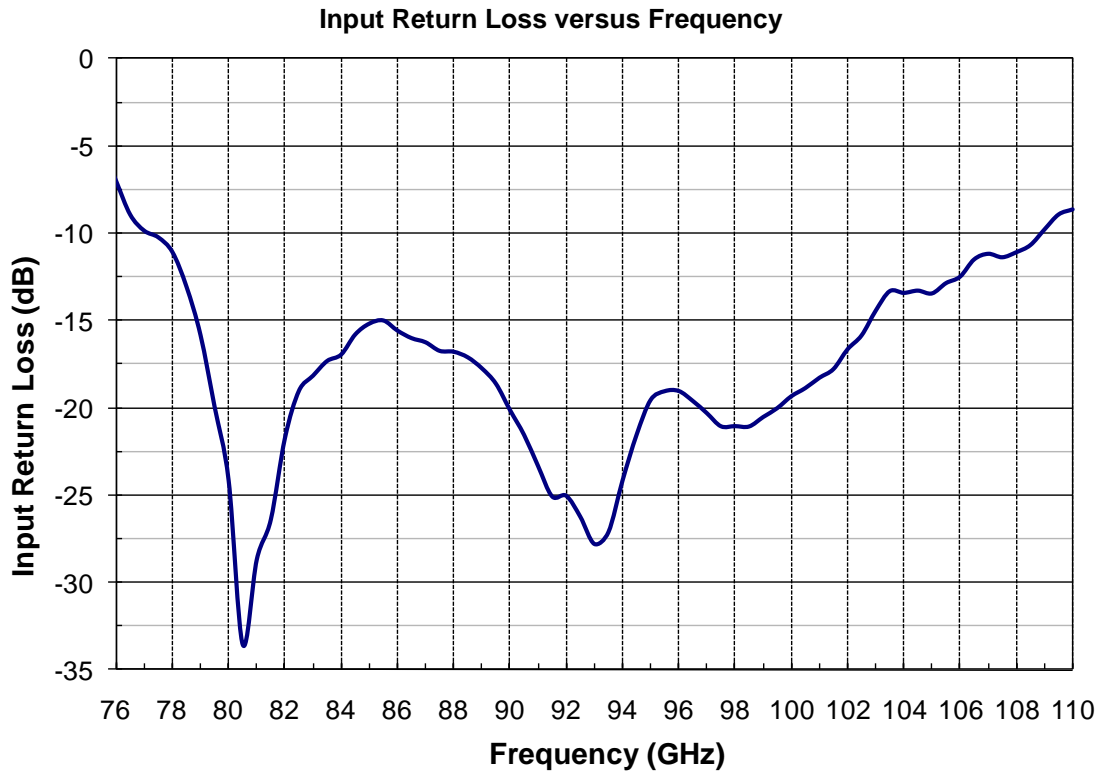
## Typical On wafer Measurements

Tamb.= +25°C, VD = 2.5V, ID = 115mA

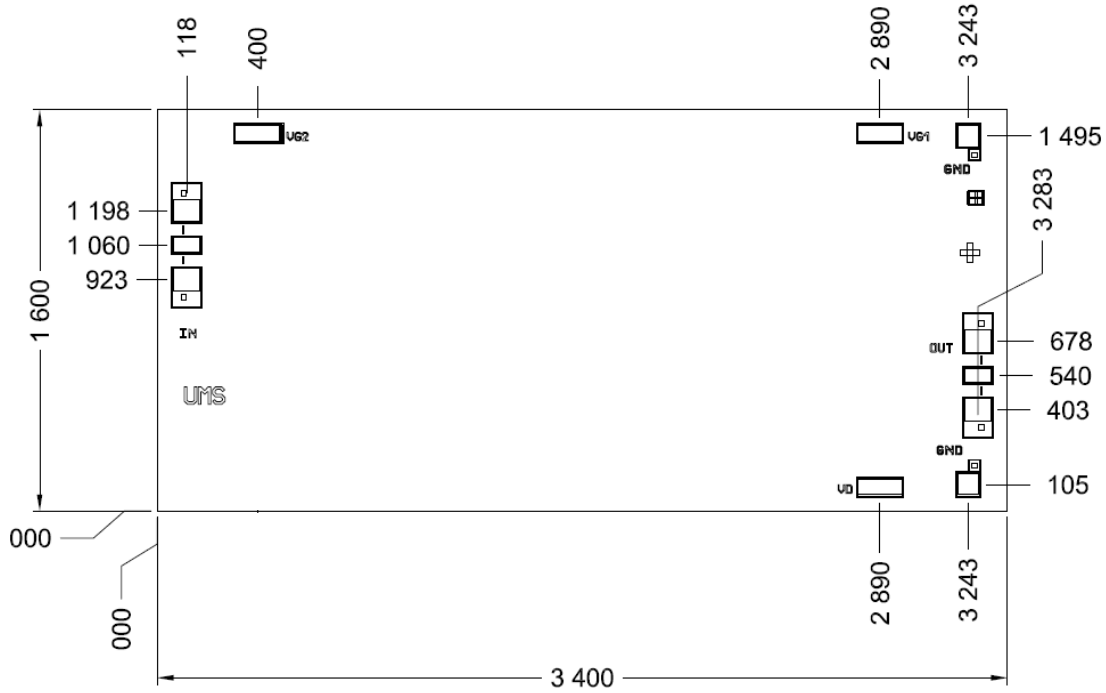


## Typical On wafer Measurements

Tamb.= +25°C, VD = 2.5V, ID = 115mA



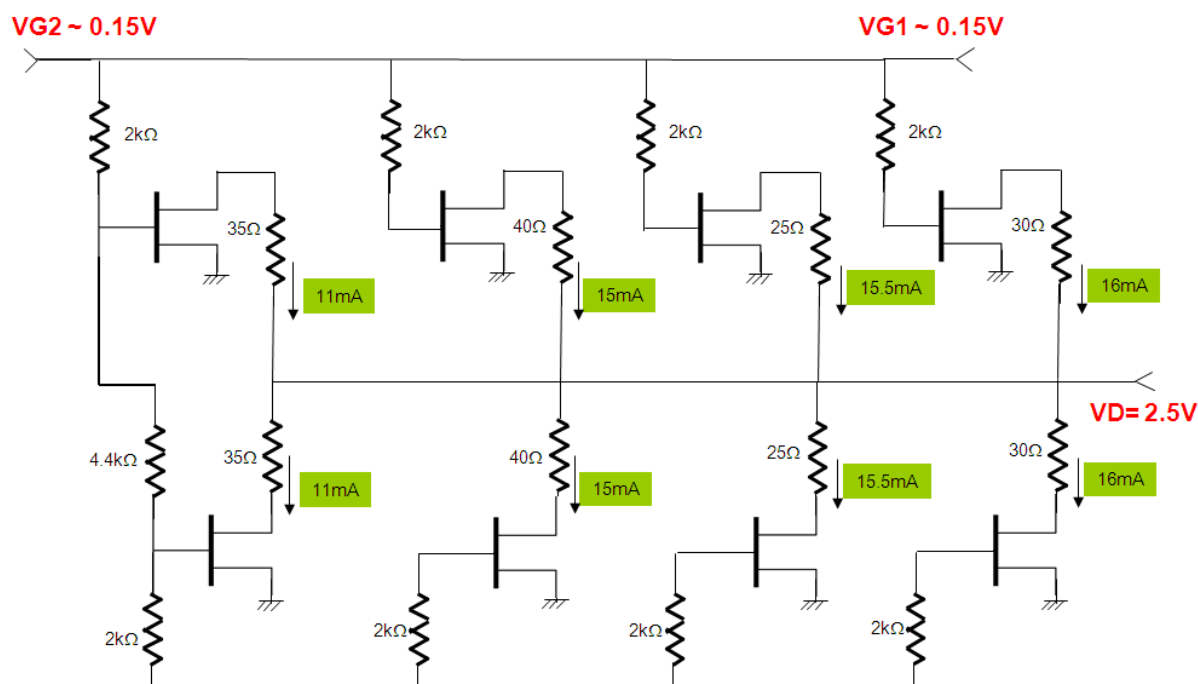
## Mechanical data



Chip thickness: 70μm  
 DC pad size: 190x80μm  
 RF pad size: 122x72μm

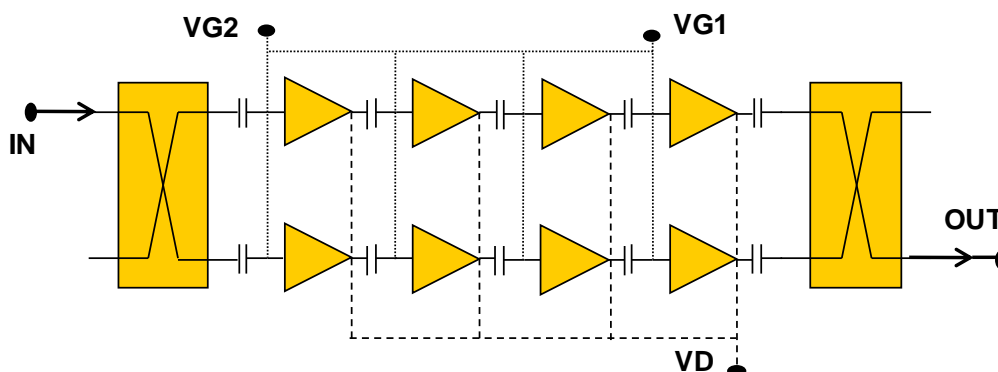
Chip size: 3400x1600 ±35μm  
 All dimensions are in micrometers

**DC Schematic**



**Notes**

VD supply voltage is common for the 4 stages of the amplifier.  
 VG1 and VG2 pads are linked in the circuit so the gate supply voltage can be apply either on VG1 or VG2.



## Recommended ESD management

Refer to the application note AN0020 available at <http://www.ums-gaas.com> for ESD sensitivity and handling recommendations for the UMS products.

## Recommended environmental management

UMS products are compliant with the regulation in particular with the directives RoHS N°2011/65 and REACH N°1907/2006. More environmental data are available in the application note AN0019 also available at <http://www.ums-gaas.com>.

## Ordering Information

Chip form: CHA1008-99F/00

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